



Newsletter



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CONFERENCES



PUBLICATIONS



ANNOUNCEMENTS



CALLBOARD

CEDA[®]
IEEE Council on Electronic Design Automation

**PHIL KAUFMAN AWARD
FOR DISTINGUISHED
CONTRIBUTIONS
TO EDA**

Nomination Deadline:
30 June 2026

Phil Kaufman Award Nominations

The Phil Kaufman Award honors individuals who have made a demonstrable IMPACT on the field of electronic design through contributions in Electronic Design Automation (EDA). Established in memory of industry pioneer Phil Kaufman, the award recognizes achievements in areas including technology and engineering, business leadership, industry direction, and education and mentoring.

Award recipients are recognized at an annual award dinner in Silicon Valley and are automatically inducted into the Phil Kaufman Hall of Fame.

Nomination Deadline: 30 June 2026

[Learn More](#)



CEDA Distinguished Lecturer Program

16 July 2026

Michael Niemier
University of Notre Dame

Virtual Distinguished Lecture

Strategies for Evaluating the Impact of Emerging Memory Technologies at the Application-Level

Michael Niemier

This talk will consider systematic ways to convolve application-level benchmarking efforts (which frequently leverage analysis of peripheral circuit overheads) with quantitative analysis of emerging memory device key performance indicators (KPIs) that are also of interest to industry (i.e., device self-consistency/target cell repeatability; device-to-device repeatability, targeting small 6 sigma; device retention; device endurance; read disturb; large resistance differentials). We show how array-level analysis (e.g., of peripheral overheads) can provide quantitative estimates of figures of merit (FoM) such as {array, application}-level area, latency, and energy, as well as qualitative insight as to the impact on memory KPIs. With physics-based device models and/or experimental measurements, we can further quantify both memory KPIs, as well as additional application-level FoM such as accuracy. We present our approach in this talk primarily in the context of ferroelectric devices, but will comment on other memory technologies as well.

Live Date and Time: 16 July 2026, 11:00 EDT (UTC-04:00)

Register Today

CALL FOR REGISTRATION

ADVANCED REGISTRATION ENDS:
JUNE 26, 2026



DAC 2026: Registration Open

The 63rd DAC, Chips to Systems Conference will take place in Long Beach, CA, from 26–29 July 2026. Sponsored by IEEE CEDA and ACM SIGDA, DAC continues to bring together researchers, designers, and industry leaders driving innovation across AI, machine learning, high-performance computing, automotive, mobile technologies, security, and more.

Advanced Registration Rate Deadline: 26 June 2026

[Register Today](#)



ICCAD 2026: Call for Exhibitors & Patrons!

Exhibitors and patrons are invited to join the 45th International Conference on Computer-Aided Design (ICCAD 2026).

Taking place November 8-12, 2026 in San Jose, in the heart of Silicon Valley, ICCAD brings together the global community advancing electronic design automation, integrated circuits, and system-level innovation.

Position your organization alongside the technologies and talent shaping what comes next. Engage directly with researchers, engineers, and decision-makers, and build connections that extend well beyond the conference.

Partner with ICCAD 2026



Compete in the IEEE HART HardwAIre Challenge

Looking for a hands-on engineering challenge? The IEEE HART HardwAIre Challenge is calling for teams of IEEE student members to design and build a wireless temperature monitoring sensor system that integrates AI in either the design process or the operation of the hardware.

Only 50 teams will be accepted, and the speed of your submission is a major factor in determining which teams advance into the competition. Selected teams will receive free 12-month access to Ansys hardware design software, as well as financial reimbursement to purchase components and build their prototypes.

The top three teams will earn the opportunity to present their prototypes live at an IEEE event and compete for a US\$2,000 grand prize.

Start gathering your dream team now!

Submit Today

2026 CEDA DISTINGUISHED SERVICE AWARD

David Atienza

*For distinguished service to the EDA
community and the IEEE Council on EDA.*



2026 Distinguished Service Award Winner

Congratulations to David Atienza on receiving the 2026 Distinguished Service Award for exceptional service to the EDA community and the IEEE Council on EDA.

[Learn More](#)



ESWEEK 2026

IEEE/ACM Embedded Systems Week (ESWEEK) 2026 will take place 4–9 October 2026, in Barcelona, Spain. ESWEEK is a premier event covering hardware and software design for intelligent and connected computing systems, bringing together the CASES, CODES, and EMSOFT conferences, the MEMOCODE symposium, as well as workshops, tutorials, and education classes.

The conference highlights state-of-the-art research and development in embedded systems across academia and industry.

[Learn More](#)

ICCD 2026

44th IEEE International Conference on
Computer Design

 November 16–18, 2026

 Hong Kong



ICCD 2026: Special Session and Tutorial Proposals

The 44th IEEE International Conference on Computer Design (ICCD 2026) will be held 16–18 November 2026 in Hong Kong. ICCD is a premier multidisciplinary conference covering the research, design, and implementation of computer systems and their components, including computer architecture, verification and test, design tools and methodologies, circuit design, and technology.

Researchers and practitioners are invited to contribute to ICCD 2026 through Special Session and Tutorial proposals.

Special Session Proposal Deadline: 2 July 2026

Tutorial Proposal Deadline: 4 July 2026

[Learn More](#)



**2026 CEDA
OUTSTANDING
SERVICE AWARD**

Hai "Helen" Li
*Outstanding Service to the EDA Community
as DAC General Chair in 2025*



2026 Outstanding Service Award Winner

Congratulations to Helen Li on receiving the 2026 Outstanding Service Recognition Award for exceptional commitment and service to the EDA community as DAC 2025 General Chair!

[Learn More](#)



IEEE HOST 2027: Call for Contributions

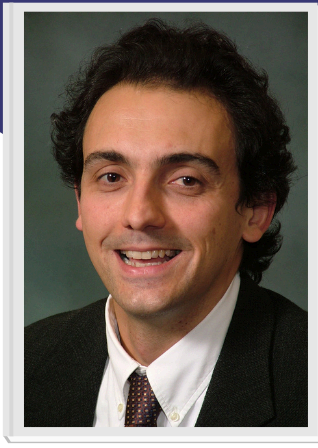
The IEEE International Symposium on Hardware Oriented Security and Trust (HOST) 2027 has opened its call for contributions. As the premier symposium for hardware security research and development, HOST brings together researchers and practitioners advancing technologies for hardware security and assurance.

HOST 2027 will be held in May 2027 in Washington, DC and welcomes original contributions across hardware security, including AI and hardware security, CAD for hardware security verification, hardware attack and defense, architecture and system security, chiplet and heterogeneous integration security, and emerging security and privacy solutions.

Fall Submission Deadline: 15 July 2026

Winter Submission Deadline: 1 November 2026

[Submit Today](#)



IEEE CEDA KEYNOTE TALK

LUCA CARLONI

COLUMBIA UNIVERSITY

CEDA Keynote Speaker for DAC 2026

The Role of Open-Source Hardware in AI for EDA

Luca Carloni

As semiconductor systems become increasingly specialized and heterogeneous, design complexity continues to grow, creating new challenges for design automation. In this talk, Luca Carloni explores how open-source hardware can help advance AI for EDA by providing the shareable artifacts, reproducible evaluation environments, and collaborative infrastructure needed to develop and validate next-generation AI-driven design tools. Drawing on his experience developing ESP, an open-source platform for heterogeneous SoC design, he discusses how open-source hardware can accelerate AI-driven workflows while helping train the next generation of hardware engineers and EDA tool developers.

Prof. Carloni is Chair of Computer Science at Columbia University and an ACM and IEEE Fellow.

KEYNOTE TALK: 28 July 2026

[Learn More](#)

WELCOME

IEEE Council on Electronic Design Automation
New Chapters



Welcome New Chapters

The IEEE Council on Electronic Design Automation is happy to welcome our new Chapters!

- Sri Sivasubramaniya Nadar College of Engineering Student Branch Chapter
- Parala Maharaja Engineering College Student Branch Chapter
- Egypt Chapter

[Learn More](#)

Conferences



MPSoC'26

International Forum on MPSoC for Software-Defined Hardware (**MPSoC 2026**)

📅 21-26 June 2026

📍 Niagara, Canada



ETS
26

European Test Symposium (**ETS 2026**)

📅 25-29 May 2026

📍 Chania, Greece



IOLTS

International Symposium on On-Line Testing and Robust System Design (**IOLTS 2026**)

📅 1-2 July 2026
📍 Polignano a Mare, Italy

DAC 2026

July 25 - 29, 2026
Long Beach, California

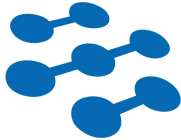
Design Automation Conference (**DAC 2026**)

📅 26-29 July 2026
📍 Long Beach, CA, USA



SBC/SBMicro/IEEE Symposium on Integrated Circuits and Systems Design (**SBCCI 2026**)

📅 24-28 August 2026
📍 Sao Paulo, Brazil



International Conference on Omni Layer Intelligent Systems (**COINS 2026**)

📅 7-9 September 2026
📍 Bologna, Italy



Symposium on Machine Learning for CAD (**MLCAD 2026**)

📅 7-9 September 2026
📍 Jeju Island, Korea (South)



Symposium on Formal Methods and Models for System Design (**MEMOCODE 2026**)

📅 8-9 October 2026
📍 Barcelona, Spain



Conference on Very Large Scale Integration (**VLSI-SoC 2026**)

📅 11-14 October 2026
📍 Limassol, Cyprus



Design, Test and Technology of Integrated Systems (**DTTIS 2026**)

📅 4-6 November 2026

📍 Hammamet, Tunisia



International Conference on Computer-Aided Design (**ICCAD 2026**)

📅 8-12 November 2026

📍 San Jose, California, USA



Contact IEEE CEDA VP of Conferences Joerg Henkel for sponsorship opportunities at vp.conferences@ieee-ceda.org.

Publications

IEEE Design & Test Special Issue

IEEE Design & Test (D&T) has announced a special issue on *Application of LLMs at the Edge: Design, Optimization, Reliability, and Security*.

Submission Deadline: 15 August 2026

[Learn More](#)

IEEE CEDA financially sponsors and co-sponsors several publications and publishes its **Currents** newsletter to inform the EDA community on industry news and research results.

Visit the individual publication pages for more information on publication scope, call for papers, and more.

Top Accessed Articles in January 2026



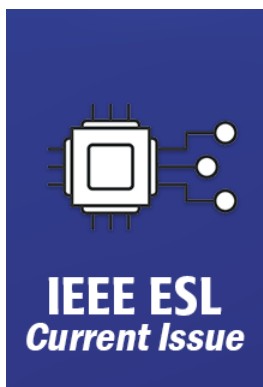
IEEE Transactions on Computer-Aided Design of Integrated Circuits and Systems

- **An Updated Assessment of Reinforcement Learning for Macro Placement**
- **MNSIM 2.0: A Behavior-Level Modeling Tool for Processing-In-Memory Architectures**
- **RTLCodeR: Fully Open-Source and Efficient LLM-Assisted RTL Code Generation Technique**



IEEE Design&Test

- **A Survey of Silicon Photonics for Energy-Efficient Manycore Computing**
- **STAR: A Mixed Analog Stochastic In-DRAM Convolutional Neural Network Accelerator**
- **Ethical Design of Computers: From Semiconductors to IoT and Artificial Intelligence**



IEEE Embedded Systems Letters

- **CHISEL: Compression-Aware High-Accuracy Embedded Indoor Localization With Deep Learning**
- **SANGRIA: Stacked Autoencoder Neural Networks With Gradient Boosting for Indoor Localization**
- **On-Device Personalization for Human Activity Recognition on STM32**



Contact IEEE CEDA VP of Publications Ian O'Connor at ian.oconnor@ec-lyon.fr or the journal's respective EiC for questions regarding CEDA-sponsored publications.

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